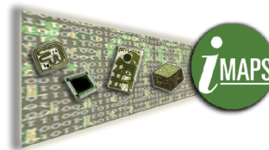
International Conference and Exhibition on

Device Packaging

www.imaps.org/devicepackaging

Radisson Fort McDowell Resort & Casino
Scottsdale, Arizona - USA
March 17 - 20, 2008



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IMAPS
International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!

Announcement and Call for Abstracts

Topical Workshop on

3D Packaging

This workshop is being held as a part of the Device Packaging Conference
March 17 - 20, 2008

Abstract Deadline: November 30, 2007

Technical Chairs:

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3D Packaging Organizing Committee:

Sitaram Arkalgud, SEMATECH
Flynn Carson, STATS ChipPAC, Inc.
Kuan-Neng Chen, IBM T.J. Watson Research Ctr.
Philip Garrou, Microelectronic Consultants of NC
Morihiro Kada, ASET - Association of Super-Advanced Electronic Technologies
Daniel D. Lu, Intel Corporation
Thorsten Matthias, EVGroup
Peter Ramm, Fraunhofer IZM, Munich
Leonard W. Schaper, University of Arkansas
Paul Siblerud, Semitool, Inc.; Program Director of EMC-3D Consortium
Lee Smith, Amkor Technology

3D Packaging Workshop Focus:

The objective of the 3D Packaging Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of 3D Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to 3D Packaging technologies, as well as to bridge the gap between the back-end wafer-level 3D integration and 3D packaging, covering wire-bonded chip stack, system-in-packaging (SiP), package-on-package (PoP), through-silicon-via (TSV) based die-to-die (or chip), die-to-wafer, and wafer-to-wafer 3D approaches.

Attendees and presenters in the past have found that the 3D Packaging Workshop is a great opportunity to meet old colleagues and to form new relationships with people in the industry. If you are working in any area of electronics packaging or microelectronics, the Workshop on 3D packaging technologies would be well worth attending. **Abstracts are being requested on the following topics:**

- Stacked Die
- Stacked Packages
- PWB Embedded Device Technologies
- Memory Cubes
- Folded Flex
- Through Silicon Vias
- Vertical Interconnects
- Thin Wafer Processing
- Assembly Processes and Handling Issues
- Testing and Probing Challenges
- Failure Analysis and Reliability
- Simulation and Modeling
- Applications and System Requirements
- Thermal Management

The 3D Packaging Workshop will also be organizing an evening Panel Session on "Roadmap of 3D Integration and Packaging", on Wednesday, March 19th, 4:00 pm - 6:00 pm, followed by a reception.

Those wishing to present in the 3D Packaging sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than November 30, 2007**, using the on-line submittal form at: www.imaps.org/abstracts.htm. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of 3D Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 12, 2008 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 17th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than November 30, 2007.**